505767970 11/12/2019

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
ZHIYONG DAI	11/12/2019
YUN LIU	11/11/2019
LVHAI HU	08/16/2019
QINGLONG ZENG	08/15/2019
WEI KANG	08/18/2019

RECEIVING PARTY DATA

Name:	TYCO ELECTRONICS (SHANGHAI) CO. LTD.
Street Address:	SECTIONS F AND G, LEVEL 1, BUILDING 15
Internal Address:	NO. 999 YINGLUN ROAD, CHINA (SHANGHAI) PILOT FREE TRADE ZONE
City:	SHANGHAI
State/Country:	CHINA
Name:	SHENZHEN AMI TECHNOLOGY CO. LTD.
Name: Street Address:	SHENZHEN AMI TECHNOLOGY CO. LTD. 1/F, H2 BUILDING, HONGFA HI-TECH INDUSTRIAL PARK
Street Address:	1/F, H2 BUILDING, HONGFA HI-TECH INDUSTRIAL PARK

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16553817

CORRESPONDENCE DATA

Fax Number: (610)889-3696

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 610-889-3699

Email: berwynipdocket@barley.com

Correspondent Name: BARLEY SNYDER

Address Line 1: 2 GREAT VALLEY PARKWAY

Address Line 2: SUITE 110

Address Line 4: MALVERN, PENNSYLVANIA 19355

PATENT REEL: 050977 FRAME: 0256

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ATTORNEY DOCKET NUMBER:	21334-2847
NAME OF SUBMITTER:	SALVATORE ANASTASI
SIGNATURE:	/Salvatore Anastasi/
DATE SIGNED:	11/12/2019

Total Attachments: 2

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PATENT REEL: 050977 FRAME: 0257

IP Portal 14-August-2019 Our Ref.: P192178.US.01

TE Ref.: TY-00666-US

Barley Snyder Ref.: 21334-2847

COMBINED DECLARATION AND ASSIGNMENT

· · · · · · · · · · · · · · · · · · ·
As a below-named inventor, I hereby declare that:
this declaration is directed to inventions and improvements disclosed in:
the attached application, or
United States application or PCT international application numberfiled on, entitled <u>Gripping System</u> ("the APPLICATION)
The APPLICATION was made or authorized to be made by me;
I believe that I am the original inventor or an original joint inventor of a claimed invention in the APPLICATION;
I have reviewed and understand the contents of the APPLICATION, including the claims, and I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37.C.F.R 1.56; AND
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.
As a below named and signing inventor, acknowledging that I have assigned or have obligations to assign the APPLICATION to:
Tyco Electronics (Shanghai) Co. Ltd. and Shenzhen AMI Technology Co., Ltd. ("ASSIGNEE"), corporations organized and existing under and by virtue of the laws of China and having their principal place of business at Sections F,G and H Level 1 Building 15, No. 999 Yinglun Road China (Shanghai), Pilot Free Trade Zone, Shanghai, China and 1/F, H2 Bldg, Hongfa Hi-tech Industrial Park, Tangtou Blvd, Shiyan, Baoan District, Shenzhen China;
for a valuable consideration, the receipt of which is hereby acknowledged, I do hereby sell, assign, transfer and set over unto the said ASSIGNEE, its successors and assigns, my full and entire right, title and interest in and to the APPLICATION, the inventions and improvements disclosed in the APPLICATION, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent to be granted and issued therefor, not only for, to and in the rights under the International Convention, and all reissues, re-examinations, renewals or extensions thereof, and I hereby authorize and request the United States Patent and Trademark Office and/or other patent office(s) to issue said Letters Patent to said ASSIGNEE, its successors and assigns, in accordance with this assignment

Legal Name	Signature	Date
DAI, Zhiyong	Tony Dan	8/1
HU, Lvhai	Samuel 44	2013.8.16
LIU, Yun	alla	8.17
ZENG, Qinglong	Man Zanx	11 8.11.2019
KANG, Wei	英语	19.8.18

REEL: 050977 FRAME: 0258

COMBINED DECLARATION AND ASSIGNMENT

As a below named and signing inventor, I hereby declare that:

this declaration is directed to inventions and improvements disclosed in:					
	the attached application, or United States application or PCT international application number 16/553,817 filed on August 28, 2019, entitled Gripping System (the APPLICATION)				
The above-identified application wa	s made or authorized to be made by me.				
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.					
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.					
As a below named and signing inventor, acknowledging that I have assigned or have obligations to assign the APPLICATION to:					
Tyco Electronics (Shanghai) Co. Ltd. and Shenzhen AMI Technology Co., Ltd. ("ASSIGNEE"), corporations organized and existing under and by virtue of the laws of China, having their principal places of business at Sections F, G and H, Level 1, Building 15, No. 999 Yinglun Road, China (Shanghai) Pilot Free Trade Zone, Shanghai, China and 1/F, H2 Bldg, Hongfa Hi-tech Industrial Park, Tangtou Blvd, Shiyan, Baoan District, Shenzhen China,					
for a valuable consideration, the receipt of which is hereby acknowledged, I do hereby sell, assign, transfer, and set over unto the said ASSIGNEE, its successors and assigns, my full and entire right, title and interest in and to the APPLICATION, the inventions and improvements disclosed in the APPLICATION, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent to be granted and issued therefor, not only for, to and in the United States of America, its territories and possessions, but also for, to and in all other countries, including all priority rights under the International Convention, and all reissues, re-examinations, renewals or extensions thereof, and I hereby authorize and request the United States Patent and Trademark Office and/or other patent office(s) to issue said Letters Patent to said ASSIGNEE, its successors and assigns, in accordance with this assignment.					
Legal Name	Signature	Date			
DAI, Zhiyong	Tong Dai	2019/11/12			
HU, Lvhai	0 7 - 1				
LIU, Yun	Yan Cia	2013.11.11			
ZENG, Qinglong	· ·				
KANG Wei					

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RECORDED: 11/12/2019

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